LCD / LCM SPECIFICATION



WINSTAR Display Co.,Ltd. 華凌光電股份有限公司



WEB: https://www.winstar.com.tw E-mail: sales@winstar.com.tw

SPECIFICATION

CUSTOMER :	~ ()
MODULE NO.:	WG320240A-TMI-VZ#

ΛDI	DDA	VED	PV.
$\Delta \Gamma I$	IVU	עטיי	DI.

(FOR CUSTOMER USE ONLY)

PCB VERSION:

DATA:

SALES BY	APPROVED BY	CHECKED BY	PREPARED BY
25	Y		

VERSION	DATE	REVISED PAGE NO.	SUMMARY	
Н	2017/02/03		Modify Information	Backlight

Winstar ay Co., LTD 華凌光電股份有限公司

RECORDS OF REVISION

DOC. FIRST ISSUE

		T	
VERSION	DATE	REVISED PAGE NO.	SUMMARY
0	2007/03/01		First issue
Α	2008/02/01		Modify contour drawing.
В	2008/05/12		Modify backlight
			information
С	2008/10/31		Modify backlight
			information
D	2012/02/22		Modify backlight
			information
Е	2013/12/30	Y	Remove IC information
F	2016/01/15		Modify Absolute Maximum
			Ratings & Response Time.
G	2016/01/27		Modify Precautions in use
			of LCD Modules & Length
	y		of cable & Static electricity
			test
Н	2017/02/03		Modify Backlight
			Information

Contents

- 1. Module Classification Information
- 2. Precautions in use of LCD Modules
- 3. General Specification
- 4. Absolute Maximum Ratings
- **5. Electrical Characteristics**
- 6. Optical Characteristics
- 7.Interface Pin Function
- 8. Contour Drawing & Block Diagram
- 9.Reliability
- 10.Backlight Information
- 11.Inspection specification
- 12. Material List of Components for RoHs
- 13. Recommendable Storage

1. Module Classification Information

① Brand: WINSTAR DISPLAY CORPORATION

② Display Type: $H \rightarrow Character Type$, $G \rightarrow Graphic Type$, $X \rightarrow TAB Type$, $O \rightarrow COG Type$

③ Display Font: 320 * 240 dot

Model serials no.

 \bigcirc Backlight Type : N \rightarrow Without backlight T \rightarrow LED, White S \rightarrow LED, High light White

 $B \rightarrow EL$, Blue green $A \rightarrow LED$, Amber $L \rightarrow LED$, Full color $D \rightarrow EL$, Green $R \rightarrow LED$, Red $J \rightarrow DIP$ LED, Blue $W \rightarrow EL$, White $O \rightarrow LED$, Orange $K \rightarrow DIP$ LED, White

 $M\rightarrow EL$, Yellow Green $G\rightarrow LED$, Green $E\rightarrow DIP$ LED, Yellow Green

F \rightarrow CCFL, White P \rightarrow LED, Blue H \rightarrow DIP LED,Amber Y \rightarrow LED, Yellow Green X \rightarrow LED, Dual color I \rightarrow DIP LED, Red

 $G \rightarrow LED$, Green $C \rightarrow LED$, Full color

© LCD Mode : B→TN Positive, Gray V→FSTN Negative, Blue

N→TN Negative, T→FSTN Negative, Black

L→VA Negative D→FSTN Negative (Double film)

 $H \rightarrow HTN$ Positive, Gray $F \rightarrow FSTN$ Positive $I \rightarrow HTN$ Negative, Black $K \rightarrow FSC$ Negative $U \rightarrow HTN$ Negative, Blue $S \rightarrow FSC$ Positive

 $M \rightarrow STN$ Negative, Blue $E \rightarrow ISTN$ Negative, Black $G \rightarrow STN$ Positive, Gray $C \rightarrow CSTN$ Negative, Black $Y \rightarrow STN$ Positive, Yellow Green $A \rightarrow ASTN$ Negative, Black

② LCD Polarize Type/ A→Reflective, N.T, 6:00 H→Transflective, W.T,6:00

Temperature D \rightarrow Reflective, N.T, 12:00 K \rightarrow Transflective, W.T,12:00 range/ View G \rightarrow Reflective, W. T, 6:00 C \rightarrow Transmissive, N.T,6:00 direction J \rightarrow Reflective, W. T, 12:00 F \rightarrow Transmissive, N.T,12:00

B \rightarrow Transflective, N.T,6:00 I \rightarrow Transmissive, W. T, 6:00 L \rightarrow Transmissive, W.T,12:00

Special Code
V : Build in negative voltage

Z:IC NT7086

#:Fit in with the ROHS Directions and regulations

2. Precautions in use of LCD Modules

- (1) Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2)Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3)Don't disassemble the LCM.
- (4)Don't operate it above the absolute maximum rating.
- (5)Don't drop, bend or twist LCM.
- (6) Soldering: only to the I/O terminals.
- (7) Storage: please storage in anti-static electricity container and clean environment.
- (8) Winstar have the right to change the passive components, including R3,R6 & backlight adjust resistors. (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (9) Winstar have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Winstar have the right to modify the version.)
- (10) To ensure the stability of the display screen, please apply screen saver after showing 30 mins of fixed display content.

3.General Specification

Item	Dimension	Unit
Number of dots	320 x 240	_
Module dimension	160.0 x 109.0 x 13.0 (MAX)	mm
View area	122.0 x 92.0	mm
Active area	115.18 x 86.38	mm
Dot size	0.34 x 0.34	mm
Dot pitch	0.36 x 0.36	mm
LCD type	STN Negative, Blue Transmissive (In LCD production, It will occur slightly color difference only guarantee the same color in the same bate	
Duty	1/240	
View direction	6 o'clock	
Backlight Type	LED White	

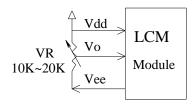
4.Absolute Maximum Ratings

Item	Symbol	Min	Тур	Max	Unit
Operating Temperature	T_{OP}	-20	_	+70	$^{\circ}\!\mathbb{C}$
Storage Temperature	T_{ST}	-30	_	+80	$^{\circ}\!\mathbb{C}$
Input voltage	$V_{ m IN}$	-0.3	_	V _{DD} +0.3	v
Supply Voltage For Logic	V _{DD} -V _{SS}	-0.3	_	7.0	V
Supply Voltage For LCD	V_{DD} - V_{0}	0	_	30	V

5.Electrical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage For Logic	$V_{ m DD} ext{-}V_{ m SS}$	_	2.7	_	5.5	V
		Ta=-20°C	_	_	26.2	V
Supply Voltage For LCD *Note	V_{DD} - V_0	Ta=25°C	23.0	23.6	24.2	V
Note		Ta=+70°C	22.1	_	4	V
Input High Volt.	V_{IH}	_	$0.8V_{\mathrm{DD}}$	_	V_{DD}	V
Input Low Volt.	V _{IL}	_	0	~ C	$0.2V_{\mathrm{DD}}$	V
Output High Volt.	V_{OH}	_	V _{DD} -0.4		_	V
Output Low Volt.	V_{OL}	-	1	_	0.4	V
Supply Current	I_{DD}	~	60.0	75.0	80.0	mA

^{*}Note: Please design the VOP adjustment circuit on customer's main board

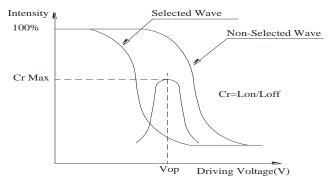


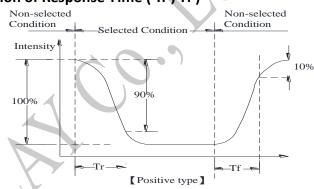
6.Optical Characteristics

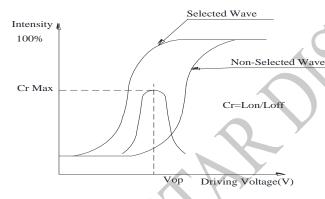
Item	Symbol	Condition	Min	Тур	Max	Unit
View Angle	θ	CR≧2	0	_	20	$\phi = 180^{\circ}$
	θ	CR≧2	0	_	40	$\phi = 0^{\circ}$
	θ	CR≧2	0	—	30	$\phi = 90^{\circ}$
	θ	CR≧2	0	_	30	$\phi = 270^{\circ}$
Contrast Ratio	CR	_	_	3	_	_
Response Time	T rise	_	_	200	300	ms
	T fall	_	_	250	350	ms

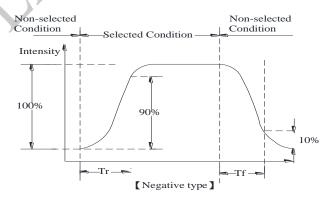
Definition of Operation Voltage (Vop)

Definition of Response Time (Tr, Tf)









Conditions:

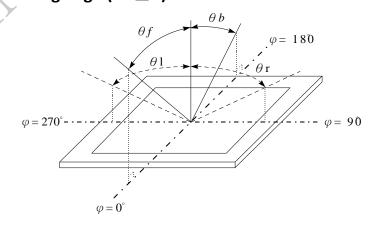
Operating Voltage : Vop

Viewing Angle(θ , φ): 0° , 0°

Frame Frequency: 64 HZ

Driving Waveform: 1/N duty, 1/a bias

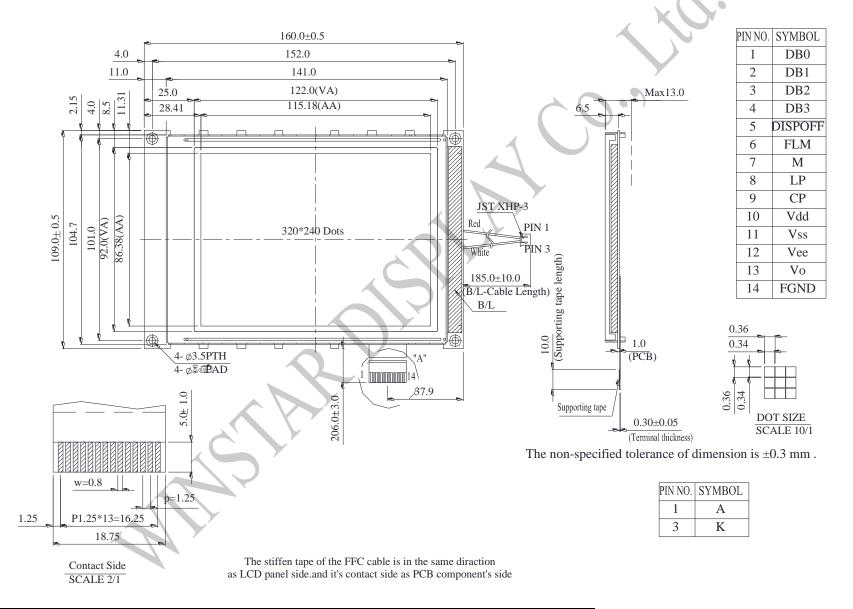
Definition of viewing angle(CR≥2)

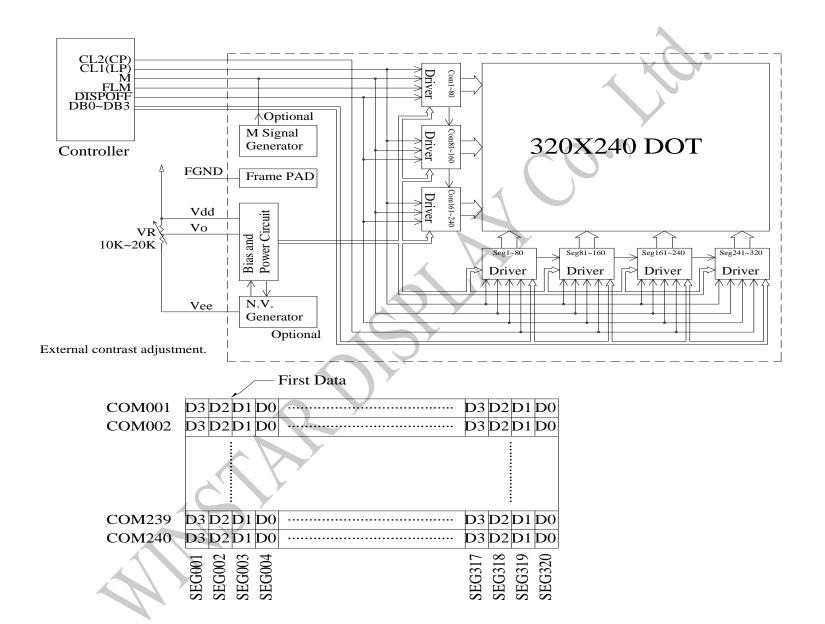


7.Interface Pin Function

		1		
Pin No.	Symbol	Level	Description	
1	DB0	H/L	Data bus line	
2	DB1	H/L	Data bus line	
3	DB2	H/L	Data bus line	
4	DB3	H/L	Data bus line	
5	DISPOFF	H/L	H: Display ON, L: Display OFF	
6	FLM	H/L	Scan start-up signal	
7	M	H/L	Frame reverse signal(alternate signal)	
8	LP	H to L	Data latch pulse	
9	СР	H to L	Data shift pulse	
10	V_{DD}		Power supply for Logic	
11	V_{SS}	0V	Ground	
12	V_{EE}	_	Negative voltage output	
13	Vo	(Variable)	Driving voltage for LCD	
14	FGND		Frame Ground	

8.Contour Drawing & Block Diagram





9.Reliability

Content of Reliability Test (Wide temperature, -20°C~70°C)

	Environmental Test		
Test Item	Content of Test	Test Condition	Not e
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80°C 200hrs ▲	2
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-30°C 200hrs	1,2
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70°C 200hrs	
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20°C 200hrs	1
High Temperature/ Humidity storage	The module should be allowed to stand at 60 °C,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60°C,90%RH 96hrs	1,2
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation -20°C 25°C 70°C 30min 5min 30min 1 cycle	-20°C/70°C 10 cycles	
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude: 1.5mm Vibration Frequency: 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3
Static electricity test	Endurance test applying the electric stress to the terminal.	$VS=\pm600V(contact),\\ \pm800v(air),\\ RS=330\Omega\\ CS=150pF\\ 10\ times$	

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal

Temperature and humidity after remove from the test chamber.

Note3: The packing have to including into the vibration testing.

10.Backlight Information

Specification

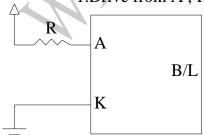
PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	TEST CONDITION
Supply Current	ILED	40	128	160	mA	V=3.5V(Note 1)
Supply Voltage	V	3.4	3.5	3.6	V	- × O
Reverse Voltage	VR	_	_	5	V	-
Luminance (Without LCD)	IV	380	420	_	CD/M ²	ILED=128mA
LED Life Time					1	ILED=128mA
(For Reference	_	_	50K	-	Hr.	25°C,50-60%RH,
only)						(Note 2)
Color	White			V Y		

Note: The LED of B/L is drive by current only, drive voltage is for reference only. drive voltage can make driving current under safety area (current between minimum and maximum).

Note 1: Supply current minimum value is only for reference since LED brightness efficiency keeps enhancing. Current consumption becomes less and less to achieve the same luminance

Note 2:50K hours is only an estimate for reference.

LED $B\L$ Drive Method 1.Drive from A , K



11.Inspection specification

Missing vertical, horizontal segment, segment contrast defect. Missing character , dot or icon. Display malfunction. No function or no display. Current consumption exceeds product specifications. LCD viewing angle defect. Mixed product types. Contrast defect. Mixed product types. Contrast defect. 2.1 White and black spots on display ≤ 0.25mm, no more than three white or black spots present. 2.2 Densely spaced: No more than two spots or lines within 3mm 3.1 Round type : As following drawing Acceptable Q TY Φ=(x + y) / 2 Φ≤0.10 Accept no dense
Display malfunction. No function or no display. Current consumption exceeds product specifications. LCD viewing angle defect. Mixed product types. Contrast defect. Spots on LCD (display only) Black or white spots on LCD (display only) Black or white spots on LCD (display only) 2.1 White and black spots on display ≤0.25mm, no more than three white or black spots present. 2.2 Densely spaced: No more than two spots or lines within 3mm 3.1 Round type : As following drawing Size Acceptable Q TY D=(x+x)/2
Testing Current consumption exceeds product specifications. LCD viewing angle defect.
Testing Current consumption exceeds product specifications. LCD viewing angle defect. Mixed product types. Contrast defect. Black or white spots on LCD (display only) 2.1 White and black spots on display ≤0.25mm, no more than three white or black spots present. 2.2 Densely spaced: No more than two spots or lines within 3mm 3.1 Round type: As following drawing Acceptable Q TY D=(x+y)/2
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Mixed product types. Contrast defect. 2.1 White and black spots on display ≤ 0.25 mm, no more than three white or black spots present. 2.2 Densely spaced: No more than two spots or lines within 3mm 3.1 Round type: As following drawing Acceptable Q TY $O = (x + y)/2$
Contrast defect. Black or white spots on LCD (display only) Contrast defect. 2.1 White and black spots on display ≤ 0.25 mm, no more than three white or black spots present. 2.2 Densely spaced: No more than two spots or lines within 3mm 3.1 Round type: As following drawing SIZE Acceptable Q TY
Black or white spots on LCD (display only) 2.1 White and black spots on display ≤ 0.25 mm, no more than three white or black spots present. 2.2 Densely spaced: No more than two spots or lines within 3mm 3.1 Round type: As following drawing Acceptable Q TY
Black or white spots on LCD (display only) three white or black spots present. 2.2 Densely spaced: No more than two spots or lines within 3mm 3.1 Round type: As following drawing SIZE Acceptable Q TY
three white or black spots present. 2.2 Densely spaced: No more than two spots or lines within 3mm 3.1 Round type: As following drawing O=(x+x)/2
2.2 Densely spaced: No more than two spots or lines within 3mm 3.1 Round type : As following drawing SIZE Acceptable Q TY
3.1 Round type : As following drawing Acceptable Q TY
$\Phi = (x + y)/2$
$\Phi = (x + y)/2$
$\Phi=(x+y)/2$ $\Phi \leq 0.10$ Accept no dense
7 7 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1
$X \leftarrow 1$ 0.10 $<\Phi \le 0.20$ 2
$0.20 < \Phi \le 0.25$ 1
LCD black $\mathbf{T}^{\mathbf{Y}}$ 0.25 $< \Phi$ 0
spots, white
o3 spots,
contaminatio 3.2 Line type : (As following drawing)
n Length Width Acceptable Q TY
(non-display) W≤0.02 Accept no dense
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$
L≦2.5 0.03 < W≦0.05 2 2.5
0.05 < W As round type
Sino (h. Annumella C.TV.
If bubbles are visible, Size Φ Acceptable Q TY
judge using black spot $\Phi \le 0.20$ Accept no dense
04 specifications, not easy $0.20 \lor \Phi \ge 0.30$ 2.5
to find, must check in $0.30 \lor \Psi \ge 1.00 \lor 2$
specify direction. $1.00 < \Phi$ 0
Total Q TY 3

NO	Item	Criterion				
05	Scratches	Follow NO.3 LCD black spots, white spots, contamination				
		Symbols Define:				
		x: Chip length y:	Chip width z: Chip	thickness		
		k: Seal width t:	Glass thickness a: LCD	side length		
		L: Electrode pad length:				
		6.1 General glass chip:				
		6.1.1 Chip on panel sur	face and crack between	panels:	V •	
		z: Chip thickness	y: Chip width	x: Chip length		
06	Chipped	Z≦1/2t	Not over viewing area	x ≦ 1/8a	2.5	
	glass	1/2t < z ≤ 2t	Not exceed 1/3k	x≦1 / 8a		
		⊙ If there are 2 or more 6.1.2 Corner crack:	e chips, x is total length	of each chip.		
		z: Chip thickness	y: Chip width	x: Chip length		
		Z≦1/2t	Not over viewing area	x ≦ 1/8a		
		1/2t < z ≤ 2t	Not exceed 1/3k	x≦1/8a		
		⊙ If there are 2 or more chips, x is the total length of each chip.				

NO	Item	Criterion			AQL			
		Symbols :						
		-	Chip width z: Chip t	hickness				
				side length				
		L: Electrode pad length		J				
		6.2 Protrusion over term	inal :					
		6.2.1 Chip on electrode ¡	oad :					
			7	\				
				X				
		11	Z					
		1/200						
		The state of the s	VX.	2000				
			and resources					
		y: Chip width		z: Chip thickness				
		y≦0.5mm		$0 < z \le t$				
		6.2.2 Non-conductive po	ortion:	Y				
			n sale	الم سيد ا				
06	Glass				2.5			
	crack							
			12 V	↑ Z				
		y		3. A.				
		X		Х				
			7					
		y: Chip width	x: Chip length	z: Chip thickness				
		y≦ L	x≦1/8a	$0 < z \leq t$				
		\odot If the chipped area to	uches the ITO terminal, o	over 2/3 of the ITO must				
	-	remain and be inspected	l according to electrode	terminal specifications.				
		\odot If the product will be I	heat sealed by the custo	mer, the alignment mark no	t			
		be damaged.						
	<i>M</i> .	6.2.3 Substrate protuber	ance and internal crack.					
	1	X	y: width	x: length				
			y≤1/3L	x ≦ a				
		V						
			782					

NO	Item	Criterion	AQL		
07	Cracked glass	The LCD with extensive crack is not acceptable.	2.5		
		8.1 Illumination source flickers when lit.	0.65		
00	Backlight	8.2 Spots or scratched that appear when lit must be judged.	2.5		
80	elements	Using LCD spot, lines and contamination standards.			
		8.3 Backlight doesn't light or color wrong.	0.65		
		9.1 Bezel may not have rust, be deformed or have fingerprints,	2.5		
09	Bezel	stains or other contamination.			
		9.2 Bezel must comply with job specifications.	0.65		
		10.1 COB seal may not have pinholes larger than 0.2mm or contamination.	2.5		
		10.2 COB seal surface may not have pinholes through to the IC.	2.5		
		10.3 The height of the COB should not exceed the height	0.65		
		indicated in the assembly diagram.			
		10.4 There may not be more than 2mm of sealant outside the	2.5		
		seal area on the PCB. And there should be no more than three			
		places.			
	PCB · COB	10.5 No oxidation or contamination PCB terminals.	2.5		
10		10.6 Parts on PCB must be the same as on the production	0.65		
10	TCB COB	characteristic chart. There should be no wrong parts, missing			
		parts or excess parts.			
		10.7 The jumper on the PCB should conform to the product	0.65		
		characteristic chart.			
		10.8 If solder gets on bezel tab pads, LED pad, zebra pad or	2.5		
		screw hold pad, make sure it is smoothed down.			
		10.9 The Scraping testing standard for Copper Coating of PCB	2.5		
	1	Y			
	A	X Y			
		X * Y<=2mm ²			
		11.1 No un-melted solder paste may be present on the PCB.	2.5		
		11.2 No cold solder joints, missing solder connections,	2.5		
11	Soldering	oxidation or icicle.			
		11.3 No residue or solder balls on PCB.	2.5		
		11.4 No short circuits in components on PCB.	0.65		

NO	Item	Criterion	AQL
		12.1 No oxidation, contamination, curves or, bends on interface	2.5
		Pin (OLB) of TCP.	
		12.2 No cracks on interface pin (OLB) of TCP.	0.65
		12.3 No contamination, solder residue or solder balls on product.12.4 The IC on the TCP may not be damaged, circuits.	
		12.5 The uppermost edge of the protective strip on the interface	2.5
	General appearance	pin must be present or look as if it cause the interface pin to	
		sever.	2.5
		12.6 The residual rosin or tin oil of soldering (component or chip	
12		component) is not burned into brown or black color.	2.5
		12.7 Sealant on top of the ITO circuit has not hardened.	0.65
		12.8 Pin type must match type in specification sheet.	0.65
		12.9 LCD pin loose or missing pins.	0.65
		12.10 Product packaging must the same as specified on packaging	
		specification sheet.	0.65
		12.11 Product dimension and structure must conform to product	
		specification sheet.	0.65
		12.12 Visual defect outside of VA is not considered to be	
		rejection.	

12.Material List of Components for

RoHs

1. WINSTAR Display Co., Ltd hereby declares that all of or part of products (with the mark "#"in code), including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A: The Harmful Material List

Material	(Cd)	(Pb)	(Hg)	(Cr6+)	PBBs	PBDEs
Limited 100 1000 1000 1000 1000 1000 1000 ppm ppm ppm ppm ppm ppm ppm ppm						
Above limited value is set up according to RoHS.						

- 2.Process for RoHS requirement: (only for RoHS inspection)
 - (1) Use the Sn/Ag/Cu soldering surface; the surface of Pb-free solder is rougher than we used before.
 - (2) Heat-resistance temp. :

Reflow: 250°C,30 seconds Max.

Connector soldering wave or hand soldering: 320°C, 10 seconds max.

(3) Temp. curve of reflow, max. Temp. : 235±5°C;

Recommended customer's soldering temp. of connector: 280°C, 3 seconds.

13. Recommendable Storage

- 1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
- 2. Do not place the module near organics solvents or corrosive gases.
- 3. Do not crush, shake, or jolt the module.



	winstar <u>LCM Sample</u>	Estimate Fe	eedback Sheet					
/lodule	Number:		Page: 1					
1 \ <u>P</u>	Panel Specification:							
1.	Panel Type:	Pass	□ NG ,					
2.	View Direction:	Pass	☐ NG ,					
3.	Numbers of Dots:	Pass	☐ NG ,					
4.	View Area:	Pass	☐ NG ,					
5.	Active Area:	Pass	☐ NG ,					
6.	Operating Temperature:	Pass	□ NG ,					
7.	Storage Temperature:	Pass	□ NG ,					
8.	Others:							
2 · <u>N</u>	Mechanical Specification:		Y					
1.	PCB Size:	Pass	□ NG ,					
2.	Frame Size:	Pass	□ NG ,					
3.	Materal of Frame:	Pass	□ NG ,					
4.	Connector Position:	Pass	□ NG ,					
5.	Fix Hole Position:	Pass	□ NG ,					
6.	Backlight Position:	Pass	□ NG ,					
7.	Thickness of PCB:	☐ Pass	☐ NG ,					
8.	Height of Frame to PCB:	☐ Pass	□ NG ,					
9.	Height of Module:	Pass	□ NG ,					
10	. Others:	Pass	□ NG ,					
3 · <u>R</u>	Relative Hole Size:							
1.	Pitch of Connector :	Pass	□ NG ,					
2.	Hole size of Connector:	Pass	□ NG ,					
3.	Mounting Hole size:	Pass	□ NG ,					
4.	Mounting Hole Type:	Pass	□ NG ,					
5.	Others:	Pass	□ NG ,					
4 · <u>B</u>	acklight Specification:							
1.	B/L Type:	Pass	☐ NG ,					
2.	B/L Color:	Pass	☐ NG ,					
3.	B/L Driving Voltage (Referen	ce for LED Ty	pe):					
4.	B/L Driving Current:	Pass	☐ NG ,					
5.	Brightness of B/L:	Pass	☐ NG ,					
6.	B/L Solder Method:	Pass	☐ NG ,					
7.	Others:	Pass	☐ NG ,					
	>> Go to page 2 <<							

	winstar							
Modu	le Number:				Page: 2			
5、	5 · Electronic Characteristics of Module :							
1.	Input Voltage:		Pass		NG ,			
2.	Supply Current:		Pass		NG ,			
3.	Driving Voltage for LCD:		Pass		NG ,			
4.	Contrast for LCD:		Pass		NG ,			
5.	B/L Driving Method:		Pass		NG ,			
6.	Negative Voltage Output:		Pass		NG,			
7.	Interface Function:		Pass		NG ,			
8.	LCD Uniformity:		Pass		NG ,			
9.	ESD test:		Pass		NG,			
10.	Others:		Pass		NG,			
6、	Summary :							
	Sales signature:							

Customer Signature:

Date: / /